
Using GHS Compiler with RH850

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RH850, GHS Compiler, Linker

Introduction

When programming the Renesas RH850, the user is focusing on various, sometimes very different goals, like saving code size, improving runtime or even an improvement of real time behavior. In consequence it is a must for modern C compilers for embedded systems to offer target specific extensions like keywords and pragmas as well as special support of the features of the microcontroller.

The purpose of this document is to give recommendations on code and RAM optimization for the Renesas RH850 microcontroller family using the GHS compiler. Some recommendations in this document are general and some are specific to the RH850 or GHS compiler.

This guideline's main goal is to enable the user making efficient use of the standard GHS compiler (V6.1.4/2013.5.5 or later) targeting the Renesas RH850 MCU family.

Target Device

RH850, F1x/D1x/P1x families

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1. Common Compiler Options

1.1 MCAL recommended Options

The following set of options is agreed for testing and running the compiler, in case the Renesas MCAL package is used.

Please note: Other, non MCAL related modules may use other options!

This defines the debug level, the option -G is usually NOT required and recommended. It has to be seen as a special case. It requires min. 1kByte additional RAM and is usable for Multi Debugger only. The debug option will prevent the optimizer from being too drastic, which means loop unrolling and inlining would happen on very limited places, even if -Ogeneral or -Ospeed would be used.

```
-g
```

This option defines the basic optimization strategy. Along with -prepare_dispose and -inline_prologue and -no_callt it may provide nearly the same level of optimization as -Ogeneral, but no loop unrolling and automatic lining is done!

```
-Ospace           # in some cases, also -Ospeed might be possible
-prepare_dispose # to make sure inlined prologue is efficient
-inline_prologue # make sure that inline prologue is generated (with
                 # -Ospace)
-no_callt        # make sure that no slow callt is used
```

Enables the basic small data addressing mode (provided by the RH850 core) and makes the generated code more efficient

```
-sda=all
```

Optionally one may provide the large SDA addressing mode and advice the linker to shorten the variable access back to signed 16-bit. This makes sense for devices with more than 64kByte RAM and 64kByte constant data.

```
-large_sda
```

The next quest is to enable some more warnings, like checking the availability of prototypes or just undefined macros.

```
--prototype_errors
-Wundef
```

Only the options below are common to ALL project modules inside and outside MCAL. They may NOT be changed or altered in the system build.

```
-reserve_r2      # setting required for some tools
--short_enum     # Make enumerations non-ANSI standard shorter
                 # than integer
-dual_debug      # make sure that other source debuggers have
                 # debug access
-cpu=rh850g3m   # or use rh850g3k
```

Finally, these are the options for the linker, valid for the entire project. The options -shorten_loads and -shorten_moves make sure that 16-bit addressing mode is used wherever this is possible. This may save code size.

```
-shorten_loads  # replace 23-bit offsets with 16-bit, where possible
-shorten_moves  # replace 23-bit offsets with 16-bit, where possible
-delete         # delete functions, which are unused
```

2. RH850 Dedicated Solutions

2.1 Bit Manipulation

The RH850 core has 4 different instructions available to deal with single bits in a memory/SFR address space. This may be utilized by the compiler, if the target's address is 8-bit wide only.

2.1.1 Bit manipulation of an 8-bit location.

Use char based types of bit fields to allow bit access.

```
struct T_BIT{
    unsigned char b00:1;
    unsigned char b01:1;
    unsigned char b02:1;
    unsigned char b03:1;
    unsigned char b04:1;
    unsigned char b05:1;
    unsigned char b06:1;
    unsigned char b07:1;
};
```

2.1.2 Bit manipulation of a 16/32-bit access

Please use a base type bigger than 'char' to define single bits within a memory location allowing only 32-Bit bus access.

```
struct T_LONGBIT{
    unsigned long b00:1;
    unsigned long b01:1;
    unsigned long b02:1;
    unsigned long b03:1;
    unsigned long b04:1;
    unsigned long b05:1;
    unsigned long b06:1;
    unsigned long b07:1;
};
```

The resulting code is not using any bit instruction by default and it is NOT thread save.

In this case, a thread safe bit manipulation may be implemented with the assistance of intrinsic functions defined in the header file

```
<ghs-dir>\include\v800\v800_ghs.h
```

```
unsigned long    __INTERLOCKED_OR( volatile unsigned long *addr, unsigned long val);
unsigned long    __INTERLOCKED_AND( volatile unsigned long *addr, unsigned long val);
unsigned long    __INTERLOCKED_XOR( volatile unsigned long *addr, unsigned long val);
unsigned long    __INTERLOCKED_NOT( volatile unsigned long *addr, unsigned long val);
unsigned long    __INTERLOCKED_MOV( volatile unsigned long *addr, unsigned long val);
unsigned long    __INTERLOCKED_ANDOR( volatile unsigned long *addr, unsigned long mask,
                                     unsigned long val);
```

2.1.3 Forced Bit instruction

This last option may be found as well as intrinsic functions (for V5.x.x or later compiler only!).

```
void    __SET1( volatile char *addr, __ghs_c_int__ bitnum);
void    __CLR1( volatile char *addr, __ghs_c_int__ bitnum);
void    __NOT1( volatile char *addr, __ghs_c_int__ bitnum);
int     __TST1( volatile char *addr, __ghs_c_int__ bitnum);
```

2.2 General Hints for Code Optimization

This chapter offers some methods to write code optimized for the RH850 architecture. Here we differentiate between optimizations concerning the C-language itself and those ones having a direct influence to the bus system and core selection.

2.2.1 Language Dependent Settings

- All local variables should be of type ‘unsigned/signed int’
 - Avoid sign extension operations (results in bigger code ...)
- Transfer parameter (function parameter) should be of type ‘unsigned/signed int’ because the internal register bus size is 32-bit.
 - Avoid sign extension operations
- Don’t use ‘volatile’ attribute on local variable
- Consider large structure declarations in local context will have higher stack usage
- Put all sequences, which are used more than one time, in a function.
- Enable generic optimization `-O`
- Remove unreferenced functions `-delete`
- Inline functions, that are only called once

2.2.2 CPU Architecture dependent settings

- Use SDA memory optimization
 - no base register load required for memory access
 - Fixed constant base register addressing (‘TP’-register)
- Enable usage of prepare and dispose instructions on function prologue and epilogue. For RH850 cores, this is
 - driver option: `-prepare_dispose`
- Set “V850 Tiny Data Area” to “None”, because the special register (EP) used for this addressing mode may be allocated automatically by the compiler in a rather intelligent manner.
 - driver option: `-notda`
- Enable inlined function pro- and epilogues
 - `-inline_prologue`
- Avoid a mixture of double/float FPU operations, where possible.
 - If it is not possible, please have a look at this specification!
 - A floating point constant without ‘f’-suffix is of type double!
 - Example:

```
float ft;
...
if( ft > 1.0f) ...
```
 - Any call to a subroutine expecting float parameter(s) without prototyping will lead into a disaster.
 - The parameter is always used as the native implementation, or at least converted to it under ANSI C, thus it is handled as a type “double”.
 - As a result, it is most probably that the function will end up in a NaN exception!
(For integer this is not that meaningful, because “long” and “int” are the same size ...)
- Avoid unnecessary type conversions
- For special high- speed functions, look for 3rd party FPU algorithms
 - Maybe they offer less security features, but are faster ...

- Use the compiler option “-ffunctions”
 - This makes sure that math functions are inlined
- Some high-speed functions are used inline, but explicit calls may use the GHS runtime library, improving the safety.
 - Example:

```
return fabsf(f);      /* this results in a library call to fabsf */
```
 - Workaround:

```
#define __ifabsf(f)  ((f>0)? (f):-f)
```
- Do not try to pass local variables located in stack and its contents to higher level functions
 - The runtime environment will be invalidated as soon as the sub function is finished.
(Invalidation of stack!)

2.3 Utilize RH850 Memory models

One of the more important issues of a Core is to understand, how it may address the memory spaces. The RH850 has a mixture of 48-, 32 and 16-bit instructions, although it is a RISC type CPU. Any memory address is always addressed by using a base register plus a signed offset, either 16-bit or 23-bit. That means in case the SDA addressing mode (“-sda=all”) is selected, the base register is fixed and will not change over the whole runtime for all variables addressed by the selected SDA mode. The base register for variables in RAM is ‘gp (r4)’ and for constants located in FLASH it is ‘tp (r5)’. Since both, constants and variables are addressed by separate base pointers, it is very important that a declaration is identical to the definition of a symbol.

2.3.1 General

- All memory models can be used at the same time
- zero and small data optimization allow to access 192 KB of data
- #pragma instructions or command line switches tell the compiler which memory model it should use for data.

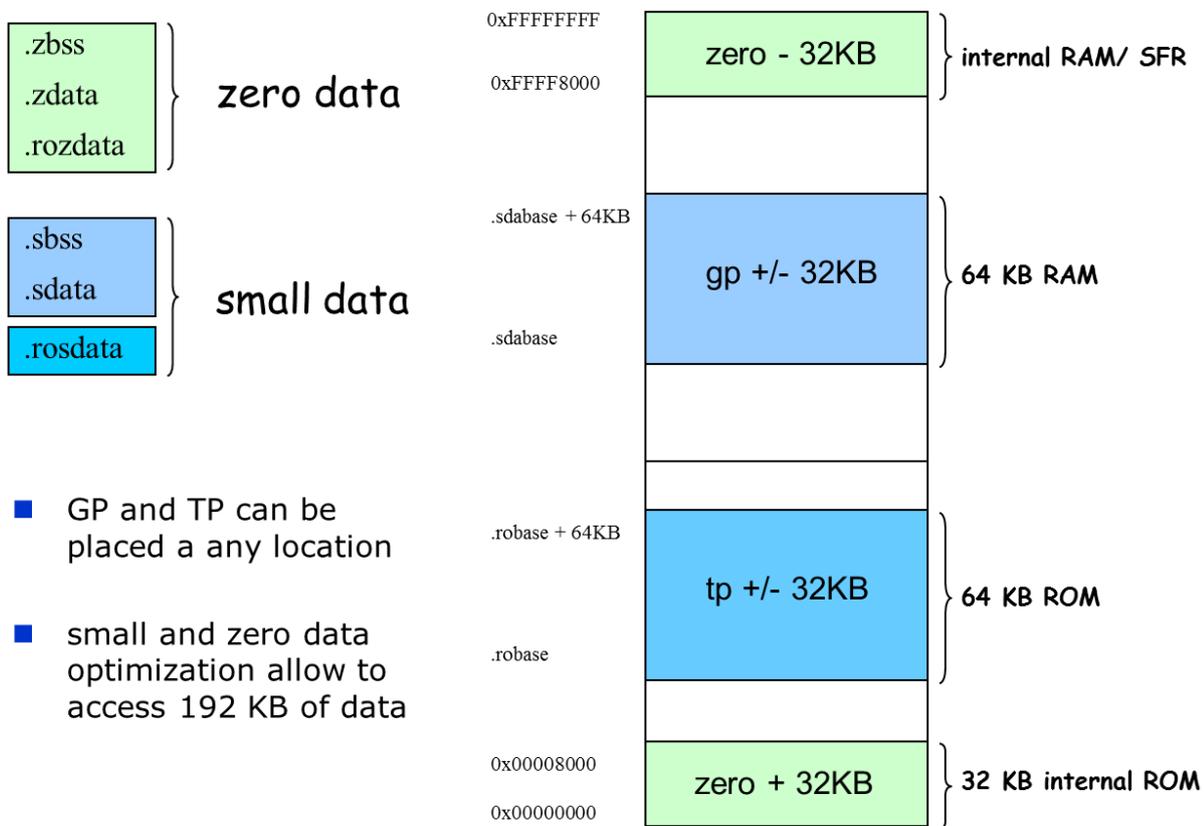


Figure 1 Memory Models

2.3.2 Mixing Memory Models

The different addressing modes SDA and ZDA are allowed to be used

- In the same module
- Across modules in the same project

Using both modes simultaneously requires strong consistency over definition and declaration of the variables.

Example:

<pre> /* * Module A.c * Definition */ __ZNEAR(const int, count1); __SNEAR(long, time); __FAR(long, OtherCount); </pre>	<pre> /* * Module A.h * Declarations */ __ZNEAR(extern const int, count1); __SNEAR(extern long, time); __FAR(extern long, OtherCount); </pre>
---	--

Table 1 Symbol Definition/Declaration

Please note that the syntax used above is derived from C99 spec., using these definitions:

```

#define PRAGMA(x)          _Pragma(#x)

#define __SNEAR(type, x)  PRAGMA( ghs startsd)  \
                          type    x;          \
                          PRAGMA( ghs endsda);

#define __ZNEAR(type, x)  PRAGMA( ghs startzda)  \
                          type    x;          \
                          PRAGMA( ghs endzda);

#define __FAR(type, x)    PRAGMA( ghs startdata) \
                          type    x;          \
                          PRAGMA( ghs enddata);

```

2.4 Useful compiler settings

- -Ospeed for runtime critical modules
 - compile to optimize execution speed
 - turns on all the -O optimizations and the loop optimizations
- -Osize -inline_prologue -no_callt -prepare_dispose for general use
 - reduce code size (similar to driver options: -Osize and -OS)
 - turns on all the -O optimizations except those which increase the code size
- Also, one may use '-O' or '-Ogeneral', although it is **not** part of any certification process ongoing for the current compiler 2013.5.5!
- Generate debug information
 - -g
 - -G does also generate debug information, but also includes additional code for debugging, which may be useful for testing and qualification. If this is used, you may call any subroutine any time in the GHS debugger's command line or script.
- Instruct the compiler to stop with preprocessor output file (*.I)
 - -P
(very useful to send to Renesas for support)
- generate library (*.a)
 - -archive
- stop with assembler code
 - -S
- Generates an assembler list file with C/C++ source code
 - -list -passource
 - This may also be used along with the '-S' option.

2.5 Helping the Compiler Optimizer

There is NO general recipe do that, but generally speaking

- Functions which are bigger, have more potential for the optimizer.
- Only bigger modules may show improved optimization

That means smaller modules with smaller functions are harder to optimize!

Therefore new optimizations

- “-Ointerproc” and
- “-Owholeprogram”

are introduced. They are optimizing the entire code, even sometimes at link stage.

- As a consequence, it is sometimes harder to debug.

In general means inlining and loop unrolling the highest speed optimizations!

2.5.1 Local Variables Should be of Type Integer

Except for arrays, structures and unions which are placed on the stack, normal local variables are placed in general purpose 32-bit registers. If a local variable is declared as a character or as a half-word and placed in a 32-bit register, then for every operation modifying this variable, the sign bit has to be set.

It is in consequence using one more instruction (2 bytes) than if it was declared as an integer. The following example is a simple illustration of what happens:

C Code

```
void read_stuct_int(void)
{
    int i0;

    for(i0 =0;i0 < 100;i0++)
    {
        S1.my_i++;
    }
}

void read_stuct_char(void)
{
    char i0;
    for(i0 =0;i0 < 100;i0++)
    {
        S1.my_i++;
    }
}
```

GHS Assembler Code

```
_read_stuct_int:
    mov     0,r2
.L193:    ld.w   zdaoff(_S1+4)[zero],r17
          add   1,r2 add 1,r17
          st.w  r17,zdaoff(_S1+4)[zero]
          addi -100,r2,zero blt
.L193    jmp   [lp]

_read_stuct_char:
    mov     0,r2
.L193:    ld.w   zdaoff(_S1+4)[zero],r17
          add   1,r2
          sxb   r2
          add   1,r17
          st.w  r17,zdaoff(_S1+4)[zero]
          addi -100,r2,zero
          blt   .L193
          jmp   [lp]
```

2.5.2 Look-up Tables

When having a long list of test in an if-statement or several if-statements, it is sometime an advantage for both speed and size to use a lookup table.

The disadvantage is that, depending on the table declaration (global, const, local...), additional RAM, ROM or stack is required e.g.:

C Code

```
int init_noLUT(int in)
{
    int out;
    in &=(8);
    if((in == 0) || (in == 2) || (in == 4) || (in == 6) || (in == 8))
        out = 0xFA;
    else out = -1;
    return out;
}

char lookup_table[9] = {1,0,1,0,1,0,1,0,1};
int init_LUT(int in)
{
    int out;
    in &=(8);
    if(lookup_table[in])
        out = 0xFA;
    else out = -1;
    return out;
}
```

GHS Assembler Code

```
_init_noLUT:
    andi    8,r6,r1
    be     .L5
    cmp    8,r1
    be     .L5
    mov    -1,r10
    jmp    [lp]

.L5:
    movea  250,zero,r10
.L2:
    jmp    [lp]

_init_LUT:
    andi    8,r6,ep
    movea  250,zero,r1
    add    gp,ep
    ld.b   sdaoff(_lookup_table)[ep],r2
    cmp    zero,r2
    cmove  -1,r1,r10
    jmp    [lp]
```

Most probably is the solution with a lookup table of higher interest, if the number of conditions is higher. Otherwise it is more likely that the ordinary comparison is faster.

2.5.3 Switch Against if/else

The code generated when using an if/else or switch directive has approximately the same size as long as the case number is less than 6. If the number of cases is bigger than 6, the compiler uses the V850 assembler instruction switch in relation with a lookup table. The code is then smaller and faster. The difference in code size between switch and if/else increases with the number of cases.

In consequence, the switch statement brings an advantage over the if/else statement when the number of case is greater than 6.

Example of using a switch statement

C-Code

```
int init_switch(int in)
{
    int out;
    in &=(5);
    switch (in)
    {
        case 0: out = 0xff; break;
        case 1: out = 0xfe; break;
        case 2: out = 0xfd; break;
        case 3: out = 0xfc; break;
        case 4: out = 0xfb; break;
        case 5: out = 0xfa; break;
        case 6: out = 0xf0; break;
        default: out = -1;
    }
    return out;
}
```

GHS Assembler Code

```
_init_switch:
    andi    5,r6,r6
    cmp     6,r6
    bnh     .L6
    mov     -1,r10
    jmp     [lp]
.L6:
    mov     r5,ep
    add     r6,ep
    ld.bu  sdaoff2(.table)[ep],r10
.L2:
    jmp     [lp]
...
.table: .byte 255,254,253,252,251,250,240
```

Only 9 lines of operation are required to acquire the desired result. Each way requires the same execution time.

Below is the sample code of a if-else-statement bundle:

C-Code

```
int init_if_else(int in)
{
    int out; in &=(5);
    if(in == 0) out = 0xff;
    else
    {
        if(in == 1) out = 0xFE;
        else {
            if(in == 2) out = 0xFD;
            else {
                if(in == 3) out = 0xFC;
                else {
                    if(in == 4) out = 0xFB;
                    else {
                        if(in == 5) out = 0xFA;
                        else {
                            if(in == 6) out = 0xF0;
                            else out = -1;
                        }
                    }
                }
            }
        }
    }
    return out;
}
```

GHS Assembler Code

```
_init_if_else:
    andi    5,r6,r6
    cmp     4,r6
    bh     .L125
    mov     r5,ep
    add     r6,ep
    ld.bu  sdaoff2(.table)[ep],r10
    jmp     [lp]
.L125:
    cmp     5,r6
    be     .L115
    movea   240,zero,r1
    cmp     6,r6
    cmovne -1,r1,r10
    jmp     [lp]
.L115:
    movea   250,zero,r10
    jmp     [lp]
...
.table: .byte 255,254,253,252,251
```

Although the compiler now utilizes the conditional mov instructions of the RH850, the advantage is still with the switch- case implementation, also from point of view regarding the readability of the code.

2.6 Pipeline Hazards

The compiler includes several intrinsic functions to handle special requirements of the system co-processors as well as requirements of the peripherals. Usually, the intrinsic functions can be found in the header file “v800_ghs.h” in this directory

```
<ghs_install_dir\include\v800
```

2.6.1 System Register Access

Certain system registers require special procedures to resolve hazards, if their content is updated and used directly after that operation. There is also a header file named “cpu.h”, which defines the access to these registers and which is reflecting the access style. In future, the header file will be part of the device file package distribution.

- **Instruction fetching**

When an instruction is to be fetched after updating a register covered by the description below, after executing the instruction to update the register, only allow the instruction fetch to start after execution of an EIRET, FERET, or SYNCI instruction.

- PSW.UM, MCFG0.SPID

When an instruction is to be fetched after updating a register covered by the description below, execute the instruction to update the register before allowing the instruction fetch to start. - All registers related to ASID and MPU (register number: SR*,5-7)

- **SYSCALL instruction**

When a SYSCALL instruction is to be executed after updating the register below, execute a SYNCPC instruction after the instruction to update the register and before the SYSCALL instruction.

- SCCFG

- **Load/Store**

When an instruction associated with Load/Store after updating the registers below, execute a SYNCPC instruction after executing the instruction to update the registers before Load/Store instruction.

- ASID, MPU protection area setting register (Register number: SR*,6-7)

- **Interrupt**

Update the registers below when interrupt is inhibited. (PSW.ID=1).

- PSW.EBV, EBASE, INTBP, FPIPR, ISPR, PMR, ICSR, INTCFG

- **Operation to clear instruction cache**

When completion of instruction cache clearance is confirmed, check the read value of the ICCTRL.ICHCLR bit.

- **FPU register update**

After executing update instruction of the registers below, execute a SYNCPC instruction.

- All FPU-related registers (Register number: SR6-11,0)”

- **Change of FPP/FPI exception mode**

When the FPP/FPI exception mode is changed, execute instructions of SYNCPC and SYNCE first, and update the register below. To update registers, proceed “FPU register update” above also.

- FPSR.PEM

- **Coprocessor instruction**

When a coprocessor instruction (floating-point operation instruction) is to be executed after updating the register below, execute instructions of EIRET, FERET or SYNCI after executing the instruction to update the registers and before executing a coprocessor instruction.

- PSW.CU0

2.6.2 Precautions for Peripheral Accesses

The accesses to peripherals that are in the same peripheral group are strictly executed in the order of the programmed sequence, i.e. a read after write will wait until the write transaction is completed.

Accesses to peripherals, which are connected to different busses or different peripheral groups, are not necessarily in the programmed order. Due to different bus latencies and buffers, a transaction that has been issued earlier may be executed after a later one.

There are two ways to ensure in software, that a peripheral access has been completed.

- **SYNCM**

The “SYNCM”-instruction waits for the completion of all data transfers (excluding the access to HBUS, instruction or other CPU transfers) from the CPU. It ensures, that the data was transferred to the peripheral, even if there are additional bus bridges or FIFO stages between the CPU and the destination register. The “SYNCM”-instruction ensures that a transaction reached its final destination by return of an acknowledge signal.

For more details on the “SYNCM”- instruction, please refer “User’s Manual: Software”.

Example:

```

...
st.w r10,0[r1]    -- Write peripheral
syncm            -- Wait until written
...

```

- **SYNCP**

The “SYNCP”-instruction ensures, that all previous instructions have been completed and the read data requested from a peripheral has arrived at the CPU.

The “SYNCP”-instruction does not ensure, that written data has reached its final destination.

Example:

```

...
st.w r10,0[r1]    -- Write peripheral register
ld.w 0[r1],r10    -- Dummy read back of the same register
syncp            -- Wait until written
...

```

3. Working with Sections

The compiler offers also different ways to allocate text or data into user defined sections. This allocation is differently handled for text and for data. Not supported is the allocation of a single global variable to a particular address.

3.1 Pulling Code Into a User Defined Section

The simplest method of changing a code section name is like this:

```
#pragma ghs section ".text"= ".mytext0"
...
void foo( void) { ... }
...
#pragma ghs section ".text"= default
```

If this is done, the section needs to be known by the linker. Best place to do this, is to add the new section to the linker directive file.

```
SECTIONS
{
    ...
    .text align(4)          :>. /* align to word */
    .mytext0 abs(0x4000) :>. /* locate the section to address 0x4000 */
    ...
}
```

3.2 Pulling Data Into A User Defined Section

Depending on the default addressing mode selected for the compiler, data is always stored in a section, which is directly related to the default one:

<i>Data Type</i>	<i>Default Section</i>	<i>Target section</i>	
		-sda=all	-zda=all
<i>Initialized data</i>	.data	.sdata	.zdata
<i>Uninitialized data</i>	.bss	.sbss	.zbss

If it is desired to place variables in the default addressing mode, like sda for example, the expression is getting simpler:

```
#pragma ghs section sbss=".mysbss"
int svar;
#pragma ghs section sbss=default

#pragma ghs section sdata=".mysdata"
int svarInit=0x55aaee11;
#pragma ghs section sdata=default
```

Please make sure, that the variable to be placed here is indeed part of the SDA (sbss) address space, otherwise the allocation will not work properly and no linker warning is issued!

3.2.1 Compiler Option Independent Allocation

The allocation of any variable into a user defined section independent of the compiler options would require a special handling. In case the addressing mode of the variable is NOT necessarily required in any special addressing mode, continue like this:

```
#pragma ghs startdata /* Makes sure that any data is moved to default*/
#pragma ghs section bss=".mybss0"
...
#pragma ghs section bss=default
#pragma ghs section data=".mydata0"
...
#pragma ghs section data=default
#pragma ghs enddata
```

Please keep in mind, that the linker directives require some adaptation to place the new sections properly.

3.3 Allocating (Module) Sections in the Linker Directive File

Another method of section allocation may be to change the directive file only, just by allocating new sections for each module having a particular section in use.

Here is an example of a method how to place all text sections used in modules of a library into a special text section:

```
.text      align(4)      :>.      /* program code area */
.libtext   align(4)      :
{          crt0.o (*.text)
          libarch.a (*.text)
}          > .          /* library code area */
```

3.4 Creating new (combined) Sections

Another method to combine the sections appearing in one or more modules into a single section means to manipulate both, the source module(s) and the linker directive file.

The example below shows a combination of both, a special vector table and a text module to be placed into the Flash area of the device.

```
.hvctext   align(256)   :          /* a new text section is created */
{
    *(.hvcall_tbl)      /* containing a table defined in assembler */
    *(.vec1_text)       /* and interrupt handlers defined in 'C' */
}              >.      /* program memory (images, fonts etc.) */
```

All sections named with “.hvcall_tbl” and “.vec1_text” are grouped and sequentially placed into the section “.hvctext”.

There is only minimum effort required in the C-modules to create such sections. The above sample is referring to two different types of sections, which are grouped and defined in assembler as well as in C:

```
#pragma ghs startdata
#pragma ghs section rodata=".hvcall_tbl"
extern const uint32_t HVC_OFFSETS[];
#pragma ghs section rodata=default
#pragma ghs enddata

/* The block below is assembler language, since it
 * incorporates techniques, a compiler cannot fulfill
 */
#pragma asm
    .section ".hvcall_tbl", "ro"
    .globl     _HVC_OFFSETS
_HVC_OFFSETS:
    .word (_HVC_Vec1 - _HVC_OFFSETS)    -- + 12
    .word (_HVC_Vec0 - _HVC_OFFSETS)    -- + 8
    .word (_HVC_Vec1 - _HVC_OFFSETS)    -- + 4
    .word (_HVC_Vec0 - _HVC_OFFSETS)    -- + 0
#pragma endasm

#pragma ghs section text=".vec1_text"
#pragma ghs noprologue
void HVC_Vec0(void)
{
    FETRAP_ENTRY();

    /* Change RBASE */
    ... ;
    FETRAP_LEAVE();
}
```

4. Variable Alignment

Green Hills provides by default the ANSI compatible alignment of variables. Thus, the linker sorts variables according to its size and alignment in memory.

The alignment can easily be given using a special 'pragma'- instruction to be placed before the variable is implemented like this:

```
#pragma alignvar(4)
unsigned short ct10;
```

Alternatively, also the 'attribute'- notation may be used:

```
__attribute__(( aligned(8) )) unsigned char xtra;
```

To do this for multiple variables, just repeat the pragma instruction

```
#pragma alignvar(4)
unsigned short ct10;
#pragma alignvar(4)
unsigned short ct10;
```

Or feel free to create new data types automatically aligning variables:

```
typedef unsigned short T_us16_64 __attribute__((aligned(8)));
typedef unsigned char T_uc16_64 __attribute__((aligned(8)));

T_us16_64 share_state0;
T_uc8_64 share_foo;
```

The above method allocates each variable of these types on 64-bit boundary!

- There is no further action required ...
- Members of structures of this type are affected, too!
- Arrays are not affected, only with starting address!

5. CPU Core Selection

GHS may select various types of cores, starting from legacy V800 cores to RH850 of the latest generation

'-cpu=' Option	Core Name	FPU type	Sample
v850	All non 'E' type cores	S/W	Very old devices ...
v850e	All E/ES/E1F types	E1F has H/W FPU (single)	Fx2/Fx3/Jx2/Jx3 and all Pho cores
v850e2v3	All E2M and E2K types	E2M core has H/W FPU	Fx4, Dx4 Fx4-L and Px4 devices
V850e3v5		H/W (double)	
rh850		S/W (default option)	
rh850g3k	G3M, G3K and G3H core family	S/W	RH850 Device Family
rh850g3m		H/W double	
rh850g3h		H/W double	

Table 2 Core Selection

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Helpdesk

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Inquiries

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Revision History

Rev.	Date	Description	
		Page	Summary
1.00	10/1/2014		Initial Version
2.00	10/27/2014		Update Table 2 Core Selection

General Precautions in the Handling of MPU/MCU Products

The following usage notes are applicable to all MPU/MCU products from Renesas. For detailed usage notes on the products covered by this document, refer to the relevant sections of the document as well as any technical updates that have been issued for the products.

1. Handling of Unused Pins

Handle unused pins in accordance with the directions given under Handling of Unused Pins in the manual.

- The input pins of CMOS products are generally in the high-impedance state. In operation with an unused pin in the open-circuit state, extra electromagnetic noise is induced in the vicinity of LSI, an associated shoot-through current flows internally, and malfunctions occur due to the false recognition of the pin state as an input signal become possible. Unused pins should be handled as described under Handling of Unused Pins in the manual.

2. Processing at Power-on

The state of the product is undefined at the moment when power is supplied.

- The states of internal circuits in the LSI are indeterminate and the states of register settings and pins are undefined at the moment when power is supplied.

In a finished product where the reset signal is applied to the external reset pin, the states of pins are not guaranteed from the moment when power is supplied until the reset process is completed.

In a similar way, the states of pins in a product that is reset by an on-chip power-on reset function are not guaranteed from the moment when power is supplied until the power reaches the level at which resetting has been specified.

3. Prohibition of Access to Reserved Addresses

Access to reserved addresses is prohibited.

- The reserved addresses are provided for the possible future expansion of functions. Do not access these addresses; the correct operation of LSI is not guaranteed if they are accessed.

4. Clock Signals

After applying a reset, only release the reset line after the operating clock signal has become stable. When switching the clock signal during program execution, wait until the target clock signal has stabilized.

- When the clock signal is generated with an external resonator (or from an external oscillator) during a reset, ensure that the reset line is only released after full stabilization of the clock signal. Moreover, when switching to a clock signal produced with an external resonator (or by an external oscillator) while program execution is in progress, wait until the target clock signal is stable.

5. Differences between Products

Before changing from one product to another, i.e. to a product with a different part number, confirm that the change will not lead to problems.

- The characteristics of an MPU or MCU in the same group but having a different part number may differ in terms of the internal memory capacity, layout pattern, and other factors, which can affect the ranges of electrical characteristics, such as characteristic values, operating margins, immunity to noise, and amount of radiated noise. When changing to a product with a different part number, implement a system-evaluation test for the given product.

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